

UNITED STATES PATENT AND TRADEMARK OFFICE



UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/008,881	11/08/2001	Mark Albert Crowder	SLA 0629	5303	
7:	590 09/30/2003				
Matthew D. Rabdau, Patent Attorney Sharp Laboratories of America, Inc. 5750 NW Pacific Rim Boulevard			EXAMINER		
			ISAAC, STANETTA D		
Camas, WA 9	8607		ART UNIT	PAPER NUMBER	
			2812		
			DATE MAILED: 09/30/2003	DATE MAILED: 09/30/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicat	ion No.	Applicant(s)				
		10/008,8	381	CROWDER, MAR	CROWDER, MARK ALBERT			
	Office Action Summary	Examine	er	Art Unit				
		Stanetta	D. Isaac	2812	_			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply								
A SH THE - Extending - If th - If No - Fail - Any	HORTENED STATUTORY PERIOD FOR RE MAILING DATE OF THIS COMMUNICATIO ensions of time may be available under the provisions of 37 CFR r SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a O period for reply is specified above, the maximum statutory per ure to reply within the set or extended period for reply will, by stareply received by the Office later than three months after the material patent term adjustment. See 37 CFR 1.704(b).	N. R 1.136(a). In no e reply within the sta riod will apply and a atute, cause the ap	event, however, may atutory minimum of will expire SIX (6) N oplication to become	y a reply be timely filed thirty (30) days will be considered time MONTHS from the mailing date of this of a ABANDONED (35 U.S.C. § 133).				
Status								
1)⊠	Responsive to communication(s) filed on <u>G</u>	04 November	<u>2001</u> .					
2a) <u></u>	This action is FINAL . 2b)⊠	This action is	s non-final.					
3)□ Disposit	Since this application is in condition for allo closed in accordance with the practice und tion of Claims				he merits is			
		tion						
7)63	 4)							
5)			idoration.					
	Claim(s) <u>5-11</u> is/are rejected.							
	Claim(s) 11 is/are objected to.							
	Claim(s) are subject to restriction and	d/or election	requirement					
	ion Papers	4,0,0,0,0,0,0,0,0	roquii omonii.					
9)[The specification is objected to by the Exam	iner.						
10)🛛	The drawing(s) filed on <u>08 November 2001</u> is	s/are: a)⊠ ad	ccepted or b)	objected to by the Examine	er.			
	Applicant may not request that any objection to	the drawing(s	s) be held in ab	eyance. See 37 CFR 1.85(a).				
11)	The proposed drawing correction filed on	is: a)∏ a	approved b)	disapproved by the Examir	ner.			
	If approved, corrected drawings are required in	reply to this C	Office action.					
12)	The oath or declaration is objected to by the	Examiner.						
Priority	under 35 U.S.C. §§ 119 and 120							
13)	Acknowledgment is made of a claim for fore	eign priority u	nder 35 U.S.0	C. § 119(a)-(d) or (f).				
a)	☐ All b)☐ Some * c)☐ None of:							
	1. Certified copies of the priority docume	ents have be	en received.					
	2. Certified copies of the priority docume	ents have be	en received ir	Application No				
* (3. Copies of the certified copies of the p application from the International See the attached detailed Office action for a l	Bureau (PCT	Rule 17.2(a)).	Stage			
14) 🔲 /	Acknowledgment is made of a claim for dome	estic priority u	ınder 35 U.S.	C. § 119(e) (to a provisiona	I application).			
	a) The translation of the foreign language Acknowledgment is made of a claim for dome	-	•		,,			
Attachmer		i		JU :==				
2) 🔲 Notic	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449) Paper No(s			ew Summary (PTO-413) Paper No of Informal Patent Application (PT				

Application/Control Number: 10/008,881 Page 2

Art Unit: 2812

DETAILED ACTION

Claim Objections

1. Claim 11 is objected to because of the following informalities: **comprises** appears twice. Appropriate correction is required.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

- 3. Claims 5-11 are rejected under 35 U.S.C. 102(e) as being anticipated by Park et al. US Patent 6,326,286.
- 4. <u>Park</u> discloses the semiconductor method substantially as claimed. See **FIGS. 1A-26E** where <u>Park</u> teaches a method of crystallizing a thin film of material comprising the steps of:
 - a) depositing a thin film of material over a substrate **260**;

Application/Control Number: 10/008,881 Page 3

Art Unit: 2812

b) irradiating regions 183-1 of the material with a first array of beamlets by positioning a mask 180 comprising the pattern of the first array of beamlets over the regions;

- c) stepping the mask **180** until a second array of beamlets is positioned at least partially overlapping the regions irradiate by the first array of beamlets;
- d) irradiating regions adjacent **183-2** to the regions irradiated by the first array of beamlets;
- e) stepping the mask until a third array if beamlets is positioned at least partially overlapping the regions irradiated by the first array of beamlets and the second array of beamlets;
 - f) irradiating regions 185-1 of the material with the third array of beamlets;
- g) stepping the mask until a fourth array of beamlets is positioned at least partially overlap regions of the material irradiated by the third array of beamlets; and
- h) irradiating regions adjacent **187-4** to the regions irradiated by the third array of beamlets.
- 5. Pertaining to claim 6, <u>Park</u> teaches the method of claim 5, wherein the mask is not rotated relative to the material during processing.
- 6. Pertaining to claim 7, <u>Park</u> teaches a method of performing a 2+2 process on a material layer deposited over a substrate comprising the steps of:
- a) providing a mask **180** comprising a first set of substantially parallel slits **180-2** and a second set of substantially parallel slits **180-3** at an angle relative to the first set of slits;
 - b) performing a first 2-shot process using the first set of slits;
 - c) translating the mask laterally; and
 - d) performing a second 2-shot process using the second set of slits.

Application/Control Number: 10/008,881

Art Unit: 2812

7. Pertaining to claim 8, <u>Park</u> teaches the method of claim 7, wherein the mask is translated laterally without rotating the substrate relative to the mask.

Page 4

- 8. Pertaining to claim 9, <u>Park</u> teaches the method of claim 7, wherein the second set of substantially parallel slits is at an approximately 90 degree angle relative to the first set of slits.
- 9. Pertaining to claim 10, <u>Park</u> teaches the method of claim 7, wherein the first set of slits comprises a first array of beamlets and a second array of beamlets, and the step of performing the first 2-shot process further comprises the steps of:
- a) irradiating the material layer through the first array of beamlets to crystallize a first set of material regions;
 - b) translating the mask laterally; and
- c) irradiating the material layer through the second array of beamlets to crystallize regions of the material layer adjacent to the first set of material regions.
- 10. Pertaining to claim 11, <u>Park</u> teaches the method of claim 10, wherein the second set of slits comprises a third array of bemalets and a fourth array of beamlets, and the step of performing the second 2-shot process further comprises the steps of:
- a) irradiating the material layer through the third array of beamlets to recrystallize regions of material;
 - b) translating the mask laterally; and
- c) irradiating the material layer through the fourth array of beamlets to crystallize regions of the material layer adjacent to the material crystallize by the third set of beamlets.

Conclusion

11. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Stanetta D. Isaac whose telephone number is 703-308-5871. The examiner can normally be reached on Monday-Friday 7:30am -5:30pm.

- 12. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, John Nebling can be reached on 703-308-3325. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.
- 13. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

Stanetta Isaac Patent Examiner September 10, 2003

John F. Niebling
Supervisory Patent Examiner
Technology Center 2800

Page 5